

R E M A R K S

Rejection Under 35 U.S.C. § 112

The Examiner's rejection under 35 U.S.C. § 112 based on the previous wording of Claim 1 has been noted, and Claim 1 has been amended to now provide for "a substrate forming a part of a display panel". As a result of this wording, wherein "having" has been replaced by --forming--, it is believed that all of the claims now comply with the requirements of 35 U.S.C. § 112.

Rejections Under 35 U.S.C. § 103

All of the claims were again rejected in view of a hypothetical combination of Applicants' Admitted Prior Art (APA) and the cited Kishigami patent. However, it is respectfully submitted that even if there existed some suggestion for such a combination of prior art teachings, that combination would not suggest the claimed invention.

Specifically, a combination of the APA and Kishigami does not contemplate the claimed requirement that

"said semiconductor device bridges the space between the substrate and the circuit board such that the driver IC is located over the space".

Also, the proposed combination does not contemplate the claimed requirement that

"The first electrode of the semiconductor device is connected to the electrode terminal on the substrate with an anisotropic conductive adhesive."

Instead, the semiconductor device of the APA is disposed directly over the circuit board so that the driver IC is disposed in its entirety over the circuit board, and is not located over the space between the circuit board and the substrate as required in Applicants' claims. Moreover, in the proposed combination by the Examiner the first electrode of the semiconductor device would not be connected to the substrate with an anisotropic conductive adhesive, but, instead, it would be connected through a conductor 32, as shown in Applicants' Fig. 13.

In summary, if one skilled in the art combined the APA with Kishigami one of two configurations would result:

- (1) The use of an anisotropic conductive adhesive would be used to attach the elements 5 of Applicants' Fig. 14 to the substrate 1bp. Such a combination, if suggested at all, would follow from the fact that the Kishigami device provides IC chips formed on a lower glass substrate, thus providing a "chip on glass type device".
- (2) Alternatively, if a suggestion existed to combine Fig. 13 of Applicants' drawings with Kishigami, one would merely provide an anisotropic conductive film between the conductor 32 of Fig. 13 and the substrate of Kishigami.

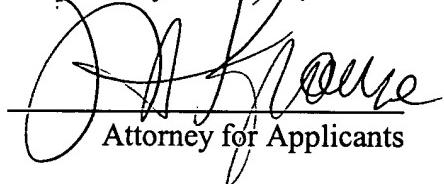
Neither of these configurations would fit the requirement for the semiconductor to bridge the space between the circuit board and the substrate of Applicants' claimed invention. More importantly, any attempt to combine the cited prior art to dispense with

the conductor 32 and to move the semiconductor over the space between the circuit board and the substrate would require the impermissible use of hindsight.

For these various reasons Applicants believe that the claims as now presented in the application are patentably distinct over the prior art, and the issuance of a formal Notice of Allowance is solicited.

Applicants' undersigned attorney may be reached in our New York Office by telephone at (212) 218-2100. All correspondence should continue to be directed to our address listed below.

Respectfully submitted,



A handwritten signature in black ink, appearing to read "John K. Knouse". Below the signature is a horizontal line.

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